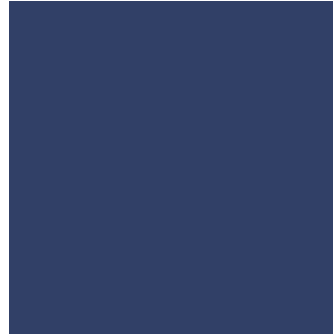




SUSS MICROTEC INVESTOR PRESENTATION

November 2013

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

- I. SUSS MicroTec at a Glance**
- II. Products and Markets
- III. Growth Opportunities
- IV. Enhanced Lithography Portfolio
- V. Financials
- VI. Outlook

- + SUSS MicroTec: A global leader in semiconductor equipment
- + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- + We are focused on high growth market segments: Semiconductors, MEMS, LEDs

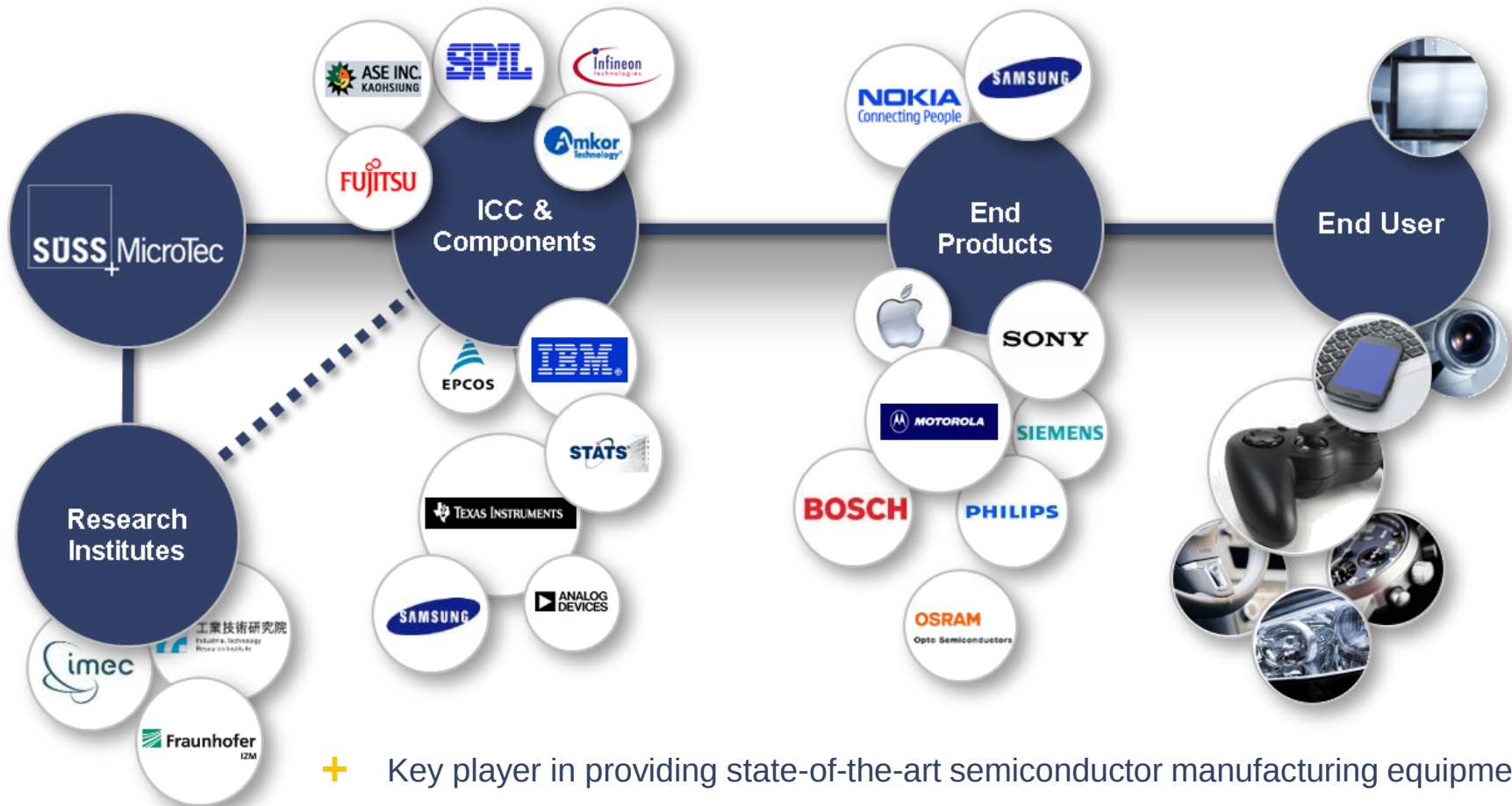
+ Key Data:

- Stock Exchange Symbol: SMHN
- Share price*: 7.83 €
- Market Cap*: 150 € million
- Net Cash, September 30, 2013: 21.9 € million

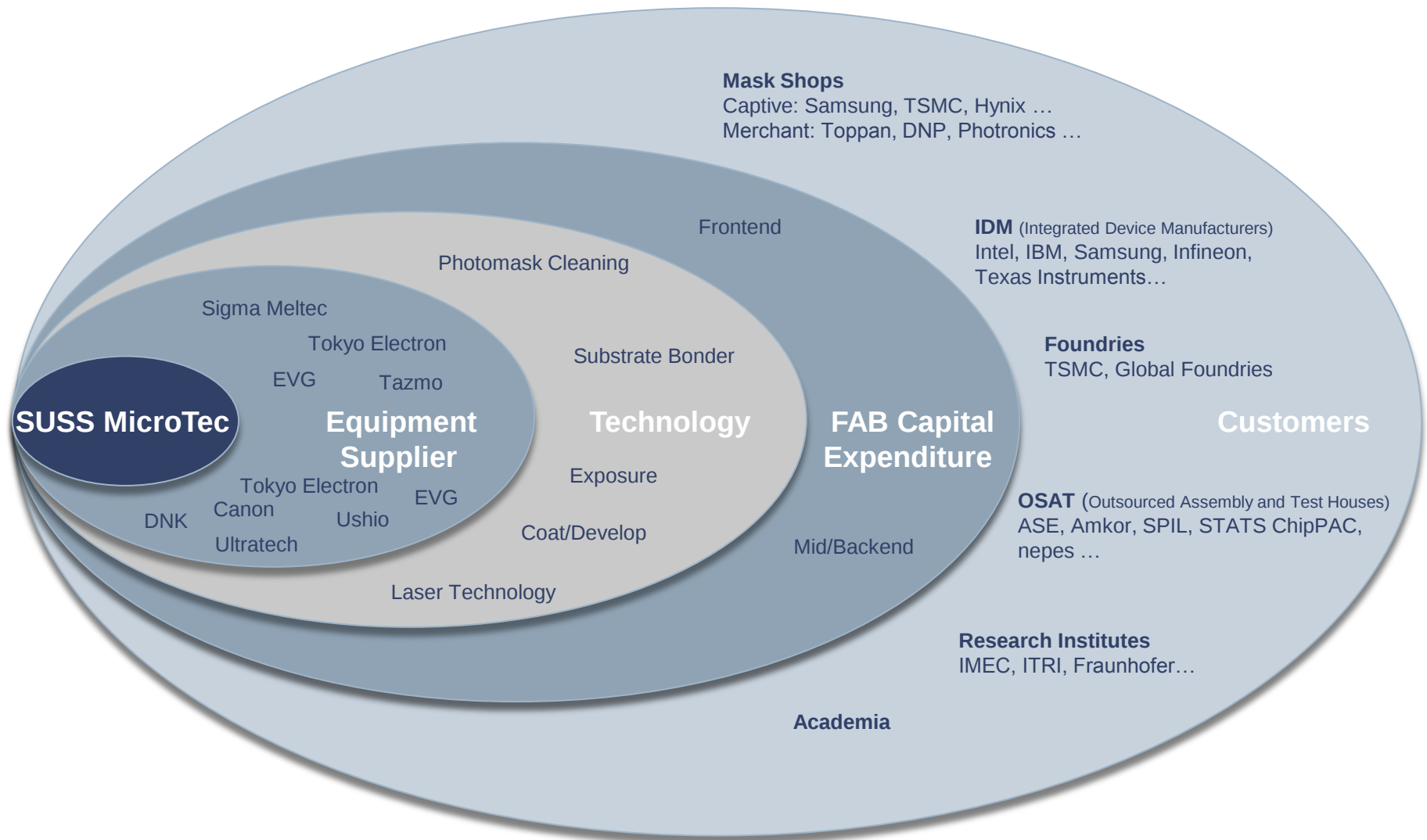


* October 31, 2013

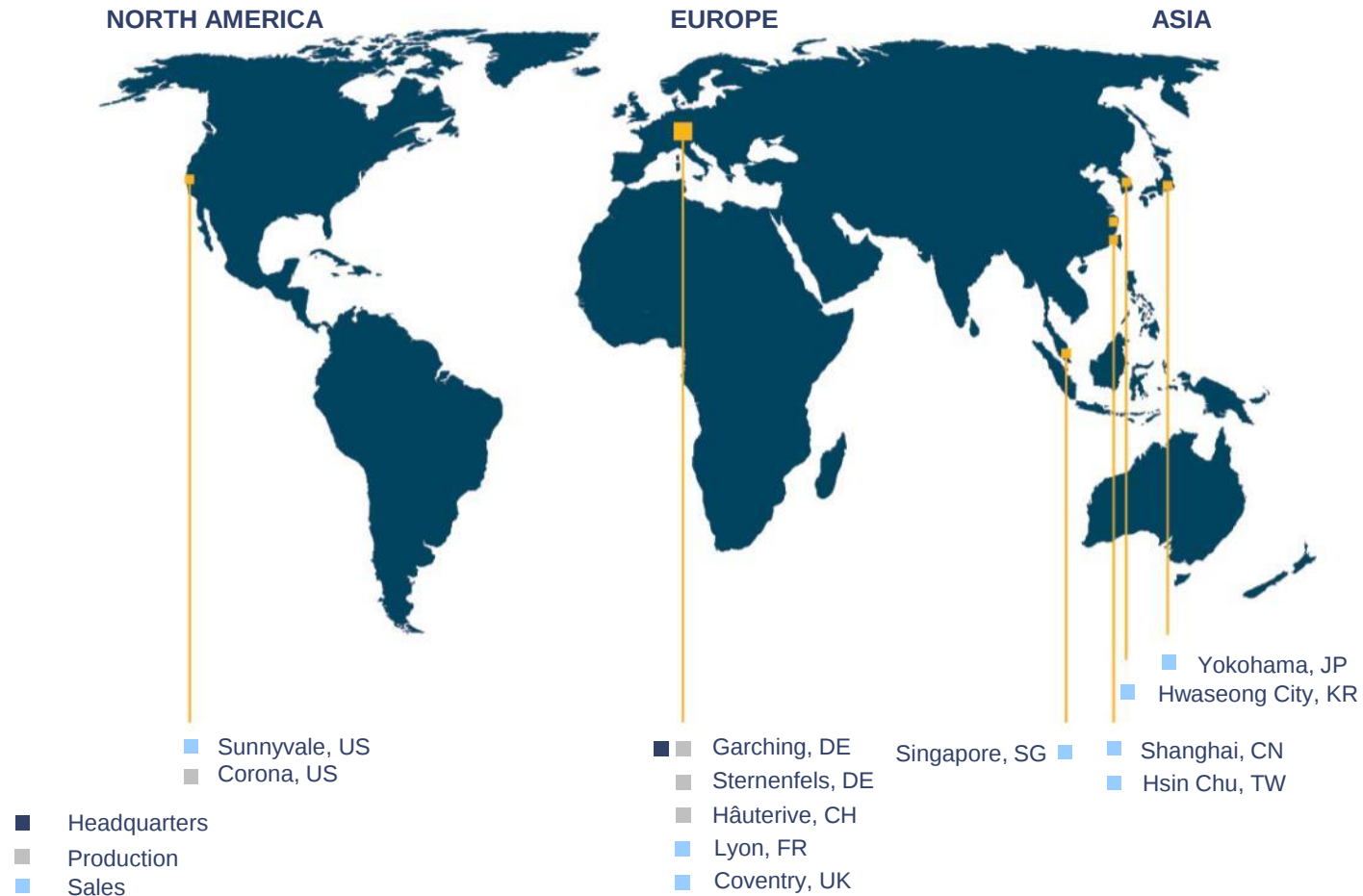
SUSS MICROTEC IN THE VALUE CHAIN



- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative process solutions with industry and R&D partners
- + Components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment



SUSS MICROTEC – A GLOBAL PLAYER



Germany



Garching

- + SUSS MicroTec HQ
- + Development/production:
 - **Mask Aligner**
 - **Bond Aligner**
- + Core competencies:
 - **Exposure**
(proximity exposure)
 - **Alignment**



Sternenfels

- + Development/production :
 - **Bonder**
 - **Coater and Developer**
 - **Photomask Equipment**
- + Core competencies:
 - **Wet processing**
 - **Wafer bonding**

USA



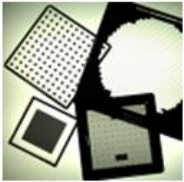
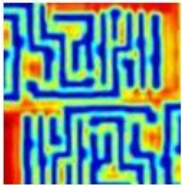
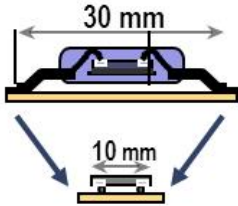
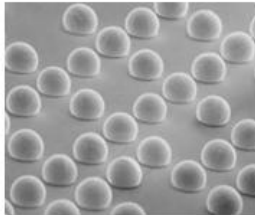
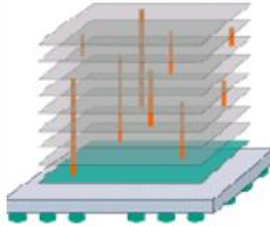
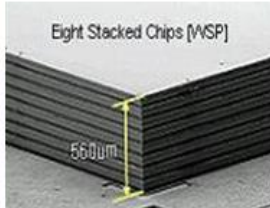
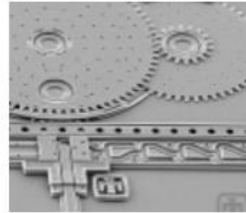
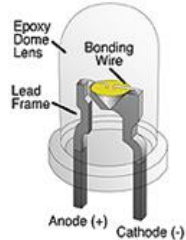
Corona

- + Development/production:
 - **Stepper/Scanner**
 - **Laser Processing**
- + Core competencies:
 - **Exposure**
(UV projection lithography)
 - **Laser Ablation**

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- II.** **Products and Markets**
- III.** Growth Opportunities
- IV.** Enhanced Lithography Portfolio
- V.** Financials
- VI.** Outlook

Semiconductors			Sensors	Lighting
Mask Manufacturing Photomask Cleaning	Advanced Packaging Micro-Bumping	3D Integration/Stacking	MEMS Computing, Automotive, Medical Applications ...	LED General Lighting, HB and UHB LED
 	 	 	 	 

SEGMENTS, PRODUCTS AND MARKETS



- + Reevaluation of the business situation in permanent bonding**
 - ongoing losses
 - expansion of the restructuring measures, which have been taken in Q2, 2013
-  **Cease production of cluster systems for permanent bonding applications**
- + Losses of the Substrate Bonding Division will be reduced significantly**
- + The successful manual permanent bonding systems are not affected**
- + Extraordinary expenses of € 6.0 million in Q2 2013**
 - € 4.6 million value adjustments on capitalized development costs from the years prior to 2008, demonstration equipment, and other inventories
 - € 1.4 million provisions for commitments and other agreements
- + Extraordinary expenses of € 8.3 million will be taken in Q4 2013:**
 - € 6.7 million for write-offs on raw materials, unfinished goods and demonstration tools
 - € 1.6 million for precautionary formed accruals for single customer projects
- + Cumulative expenses for the restructuring of permanent bonding in 2013 will amount to approximately € 14.3 million**

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TECHNOLOGY EVOLUTION



~1985...today



~1987...today

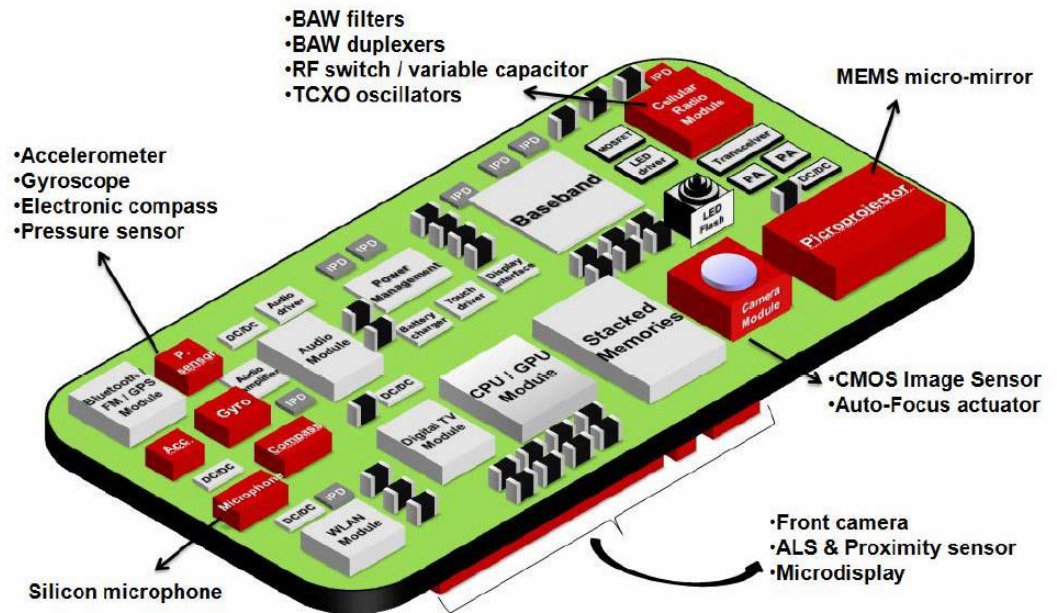
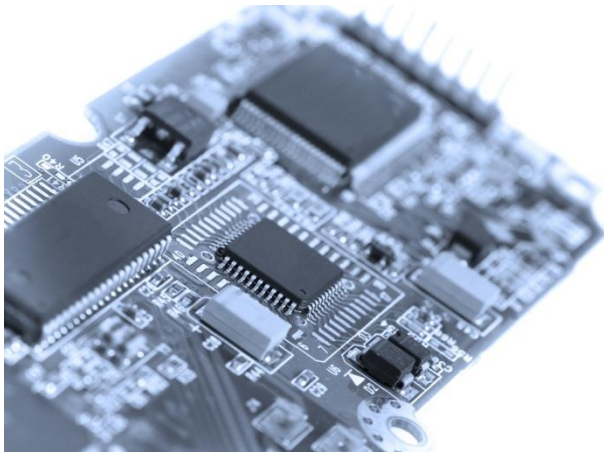


~1910...today



~1950...today

GROWTH DRIVER SMARTPHONES AND TABLETS



Source: Yole Developpement

MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle

- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- New device generations offer higher functionality



E-Mobility

- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices but also high performance ICs



Energy Efficiency

- Increase environmental awareness and rising energy prices and fuel the demand for energy efficient solutions in electricity usage i.e. lighting
- Energy efficiency in industrial production
- Smart energy management in household applications saves energy



With its strong position in the fast growing target markets 3D Integration / Advanced Packaging, LED and MEMS, SUSS MicroTec can benefit from the market developments:

Advanced Packaging

Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets

3D Integration (TSV)

Transition to production volume in the years to come

Compound Semiconductors

LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions

Segment growth 2011 - 2016E CAGR ~ 15% (Gartner and industry estimates)

SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

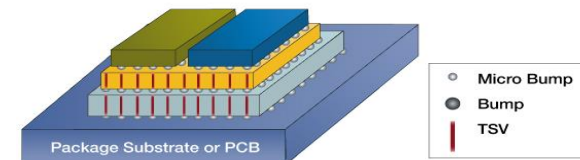
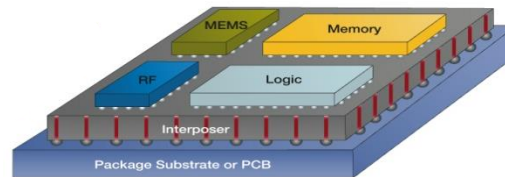
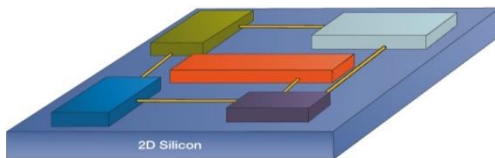
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law

3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



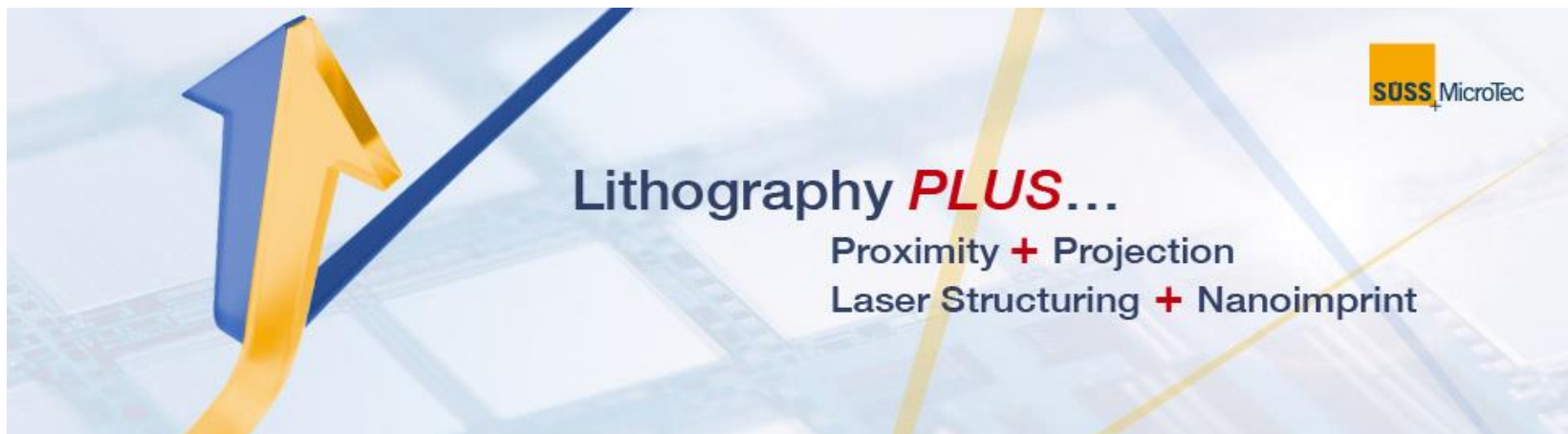
SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

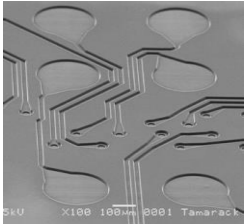
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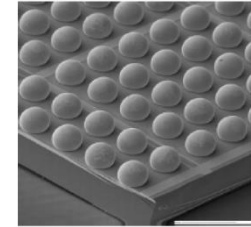
- I. SUSS MicroTec at a Glance
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- + Increasing chip performance requires the adoption of innovative lithography technologies in the semiconductor backend
- + **Not one single exposure technology fits all needs at the same time**
- + The newly acquired Stepper/Scanner products supplement our Mask Aligner product line and enlarges our technology portfolio by the key competencies UV-projection lithography and laser ablation
- + SUSS MicroOptics S.A. adds key know how for critical lithography performance improvements

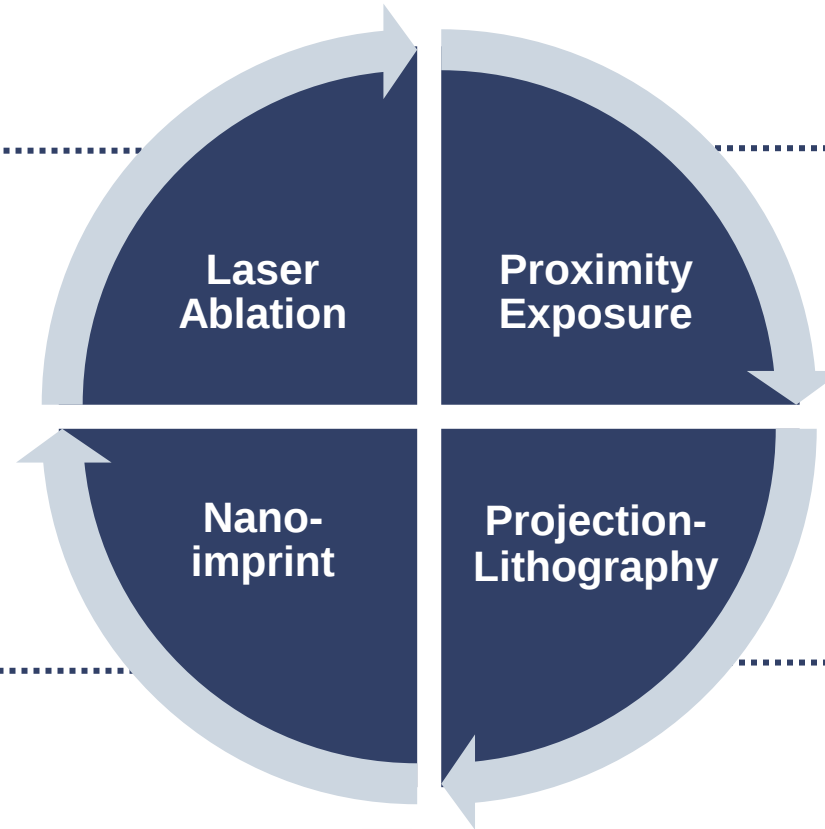




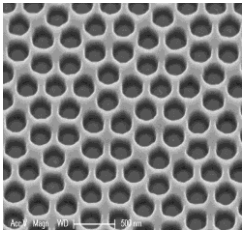
WLCSP:
Fanout WLP



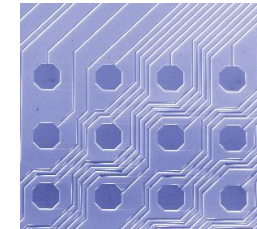
Flip Chip:
Solder Bumping



LED:
Photonic Crystals



WLCSP:
Fine pitch RDL



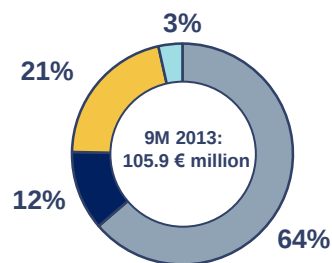
+ Only SUSS MicroTec offers complete exposure solutions for the mid-/back-end

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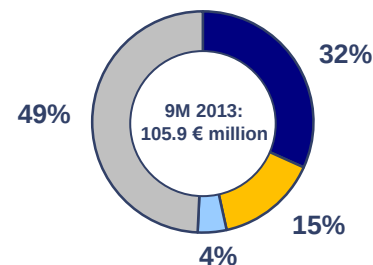


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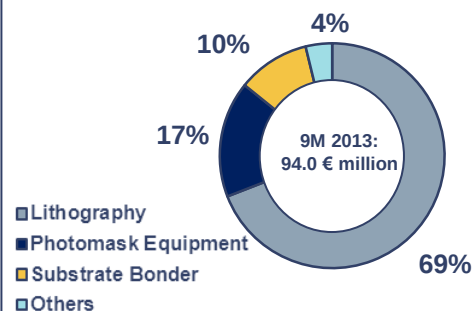
Order Entry by Segment



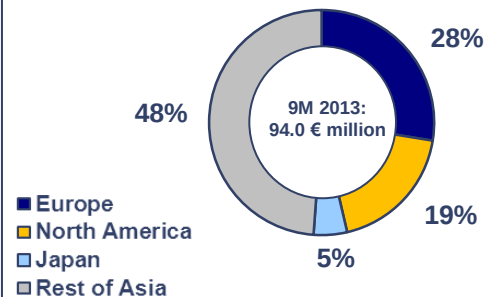
Order Entry by Region



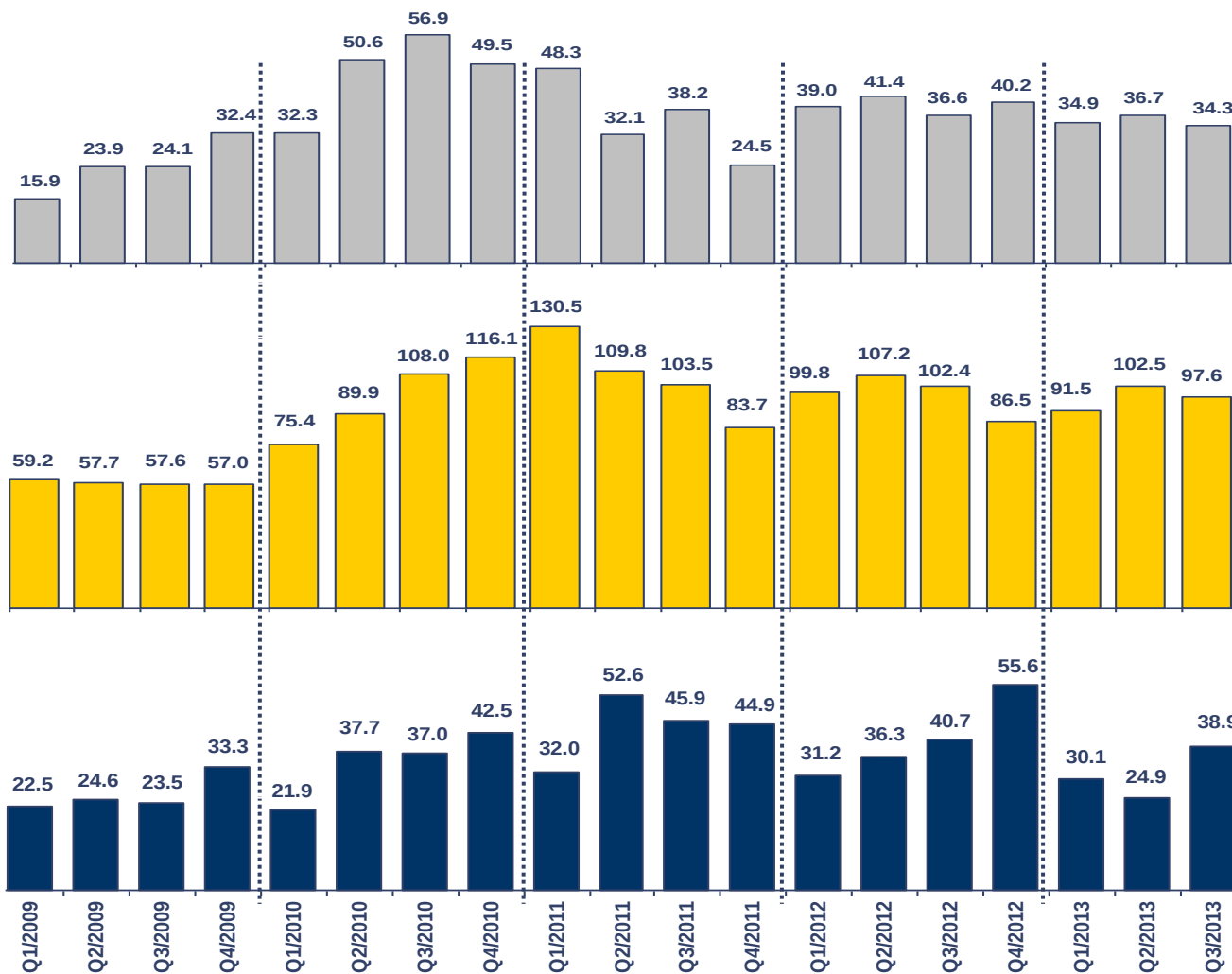
Sales by Segment



Sales by Region



LONG TERM BUSINESS DEVELOPMENT



Order Entry

in € million

2012: € 157.2 million

Order Backlog

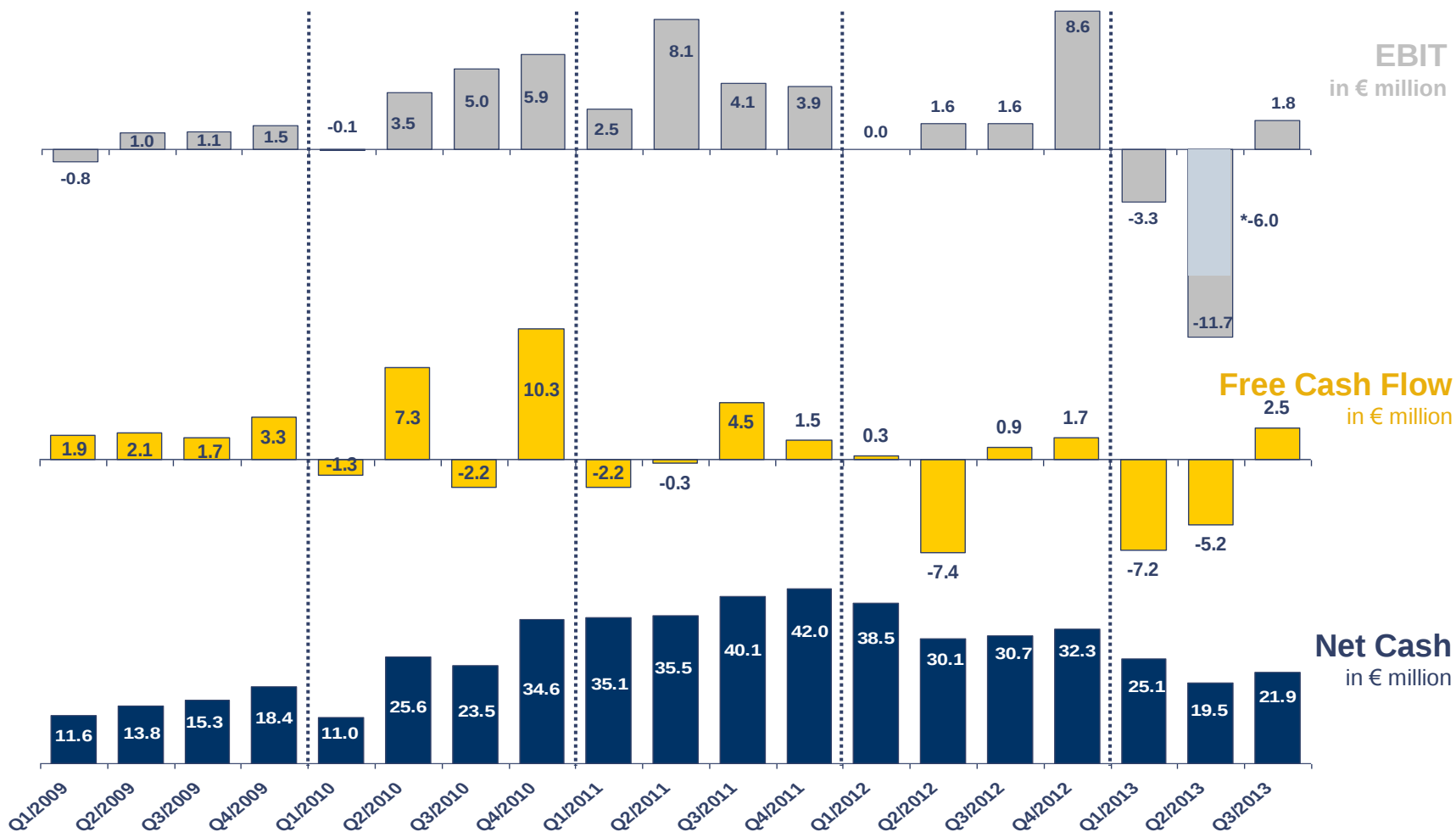
in € million

Sales

in € million

2012: € 163.8 million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from refocusing product line permanent bonding

KEY FINANCIALS

in € million	Q3 2013	Q3 2012	in %	9M 2013	9M 2012
Order Intake	34.3	36.6	-6.3%	105.9	117.0
Order Backlog 9/30	--	--	--	97.6	102.4
Revenue	38.9	40.7	-4.4%	94.0	108.2
EBIT	1.8	1.6	+12.5%	-13.2	3.1
<i>EBIT in % of Sales</i>	<i>4.6%</i>	<i>3.9%</i>	<i>--</i>	<i>-14.0%</i>	<i>2.9%</i>
EBIT (adjusted)	1.8	1.6	+12.5%	-7.2	3.5
<i>EBIT (adjusted) in % of Sales</i>	<i>4.6%</i>	<i>3.9%</i>	<i>--</i>	<i>-7.6%</i>	<i>3.2%</i>
Earnings after tax (continuing operations)	1.2	0.4	>100%	-10.5	0.8
Earnings after tax	1.2	0.4	>100%	-10.5	2.3
EPS in € (continued op.)	0.06	0.02	>100%	-0.55	0.04
Free Cash Flow*	2.5	0.9	>100%	-9.9	-6.2
Net Cash**	--	--	--	21.9	30.7
Employees 9/30	--	--	--	673	699

* before consideration of purchased interest-bearing securities , the acquisition of Tamarack and the gain out of the sale from the Test Business

** incl. stock of interest-bearing securities

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2013:

- Milestone achievement in temporary bonding
- Restructuring of product line Permanent Bonding expanded
- Further integration of SUSS MicroTec Photonic Systems

Fundamental growth in target markets

Strong competitive positioning: first or second in the target markets

Leading equipment company in the semiconductor backend, enabling “Moore’s Law” as well as “More than Moore”

Outlook

FY 2013:

- Sales of 125 – 135 € million
- EBIT: minus 22 – minus 27 million € (thereof 14.3 € million one-off charges)

Q4 2013:

- Order Intake 30 - 40 € million
- One-off charges 8.3 € million



Thank you!

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Financial Calendar 2013/2014

Nine-month Report 2013	7. Nov.
German Equity Forum, Frankfurt/Main	11. - 13. Nov
Morgan Stanley TMT Conference, Barcelona	21. - 22. Nov
KeplerCheuvreux Investment Conference, Frankfurt	20.-22. Jan
Annual Report 2013	28. Mrz.
Quarterly Report 2014	8. Mai.
Shareholders' Meeting, Haus der Bayerischen Wirtschaft, Munich	17. Jun.
Interim Report 2014	7. Aug.
Nine-month Report 2014	6. Nov.

OUR TECHNOLOGY ENABLES SUSTAINABILITY

Equipment

- SUSS MicroTec equipment is designed to efficiently use electricity and chemicals
- ReMan, the remanufacturing operation of SUSS MicroTec takes back used equipment and refurbishes it



Applications

- 3D IC and chip scaling helps reducing energy and material consumption
- LEDs for efficient lighting solutions
- MEMS applications improve performance of mobile devices and conserve energy
- Shift to renewable energies requires more power devices and high-performance ICs (e.g. for solar and wind power systems)
- Laser Ablation in lieu of photolithography (seed layer removal)

Initiatives

- Partner company of VDMA BlueCompetence initiative, a network of equipment providers in Germany, who are following a sustainable business approach
- Innovative lighting solution in Sternenfels
- Improved climatization system of cleanrooms
- Paperless invoice system

BLUECOMPETENCE

Alliance Member

Partner der Nachhaltigkeitsinitiative
des Maschinen- und Anlagenbaus

SUSS MICROTEC PRODUCT PORTFOLIO



Photomask Equipment



Coater/Developer



Wafer Bonders



**Alignment
Verification Systems**



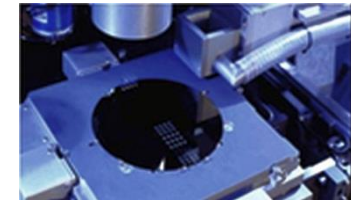
Mask Aligners



Imprinting Systems



**UV-Projection
Stepper / Scanner**



**Excimer Laser
Systems**